



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: A1609-02	DATE: 11-Oct-2016	MEANS OF DISTINGUISHING CHANGED DEVICES: ☐ Product Mark ☒ Back Mark ☐ Date Code ☐ Other
Product Affected: CABGA-96 (Refer to Attachment II for the affected part numbers)		
Date Effective: 11-Jan-2017		

Contact: IDT PCN DESK	Attachment: ☒ Yes ☐ No
E-mail: pcndesk@idt.com	Samples: Please contact your local sales representative for sample request.

DESCRIPTION AND PURPOSE OF CHANGE:

- | | |
|--|---|
| ☐ Die Technology | This notification is to advise our customers that IDT is adding OSET, Taiwan as an alternate assembly facility for parts that are currently assembled at Amkor Philippines. |
| ☐ Wafer Fabrication Process | |
| ☐ Assembly Process | There is no change to the moisture performance. |
| ☐ Equipment | |
| ☐ Material | Attachment I details the qualification results and Attachment II shows the affected list of part numbers. |
| ☐ Testing | |
| ☒ Manufacturing Site | |
| ☐ Data Sheet | |
| ☐ Other | |

RELIABILITY/QUALIFICATION SUMMARY:

Refer to qualification data shown in Attachment I.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	☐ Approval for shipments prior to effective date.
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

CUSTOMER COMMENTS:

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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ATTACHMENT I - PCN # : A1609-02

PCN Type: Manufacturing Site - Alternate Assembly Location

Data Sheet Change: None

No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT is adding OSET, Taiwan as an alternate assembly facility for parts that are currently assembled at Amkor Philippines.

The material set details of the current and alternate assembly location is as shown in Table 1.

There is no change to the moisture performance.

Table 1: Assembly Material Sets for The Existing and Alternate Assembly Location

Description	Existing (Amkor Philippines)	Add (OSET, Taiwan)
CABGA-96 (BF96, BFG96)	Die Attach: Ablestik 2300	Ablestik 2300
	Wire: 1.0 mil Gold wire	1.0 mil Gold wire
	Mold Compound: EME-G770	KE-G1250

Qualification Information and Qualification Data:

Affected Packages: CABGA-96

Assembly Material: Shown on page 2 of this attachment.

Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests.

Qualification Vehicle: CABGA-160

Test Description	Test Method	Test Results (Rej / SS)		
		Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - biased (Vccmax, 130 °C/85% RH, 96 Hrs)	JESD22-A110	0/25	0/25	0/25
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 3, 260 °C	0/25	0/25	-

* Tests were subjected to Preconditioning per JESD22-A113 prior to stress test



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ATTACHMENT II - PCN # : A1609-02

Part Number	Part Number	Part Number	Part Number
74ALVCH32244BFG	74SSTUBF32866BBFG	74ALVCH32245BFG8	SSTUA32864BHLFT
SSTUA32864BHLF	74LVCH32245ABFG8	74ALVCH32245BFG	
74SSTUBF32866BBFG8	74LVCH32245ABFG	74ALVCH32244BFG8	